

TP1500-Q (Preliminary)

High Thermally Conductive Gap Filler Pad

TP1500-Q is a 15.0W/m·K, high thermal conductive gap filler pad that low thermal resistance and excellent electrical insulation at low compression. It can work stably at -40°C~150°C and meet UL94 V-0 flame retardant grade.



Features

- 15.0W/m·K
- Ultra soft
- High compression ratio
- High electrical insulation

Typical Applications

- IGBT/BGAs
- ASICs and DSPs
- High power module
- Network Communication Devices

Typical Properties		
Properties	Attribute	Test Method
Color	Grey	Visual
Thickness(mm)	0.3 to 5.0	ASTM D374
Density (g/cc)	3.2	ASTM D792
Hardness(Shore OO)	40	ASTM D2240
Usage Temperature (°C)	- 40~150	-
Flammability	V-0	UL 94
Shelf Life(month)	12	Temperature <40°C avoid extrusion and exposure to the sun
Electrical		
Breakdown Voltage (kV/mm)	≥5.0	ASTM D149
Volume Resistivity (Ω.cm)	10 ¹²	ASTM D257
Dielectric Constant@1MHz	7.0	ASTM D150
Thermal		
Thermal Conductivity (W/m.K)	15.0	ISO22007-2



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Compression ratio curve

